



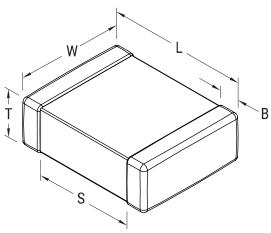
SMD Comm X8G HT150C Flex, Ceramic, 1,600 pF, 10%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1210, 1.5 mm

SMD Comm X8G HT150C Flex

SMD, MLCC, High Temperature,

SMD Chip

Ultra-Stable



S	Features	High Temperature, Ultra-Stable
	RoHS	Yes
	Termination	Flexible Termination
	Marking	No
	AEC-Q200	No
	Typical Component Weight	40 mg
Click here for the 3D model.	Shelf Life	78 Weeks
	MSL	1

**General Information** 

Series Style

Description

Dimensions	
Chip Size	1210
L	3.3mm +/-0.4mm
W	2.6mm +/-0.3mm
Т	1mm +/-0.10mm
S	1.5mm MIN
В	0.6mm +/-0.25mm

Packaging Specifications	
Packaging	T&R, 330mm, Plastic Tape
Packaging Quantity	10000

Specifications	
Capacitance	1,600 pF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	10%
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

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